



### 3A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

#### FEATURES:

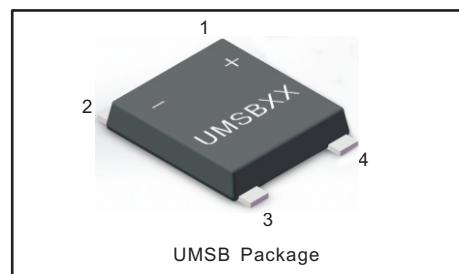
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 3.0 A
- High Surge Current Capability
- Designed for Surface Mount Application

#### PINNING

PIN	DESCRIPTION
1	Output Anode ( + )
2	Output Cathode ( - )
3	Input Pin ( ~ )
4	Input Pin ( ~ )

#### MECHANICAL DATA

- Case: UMSB
- Terminals: Solderable per MIL-STD-750, Method 2026



#### Maximum Ratings and Electrical characteristics

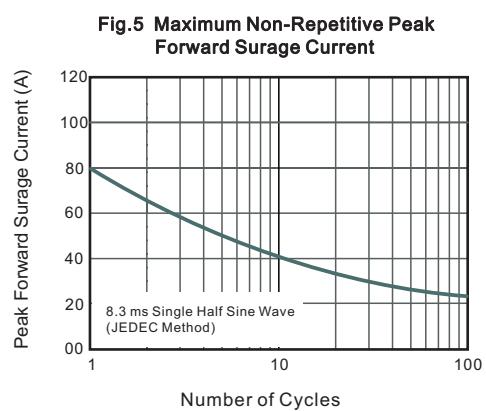
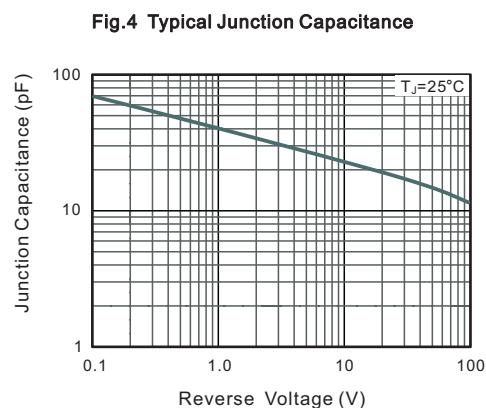
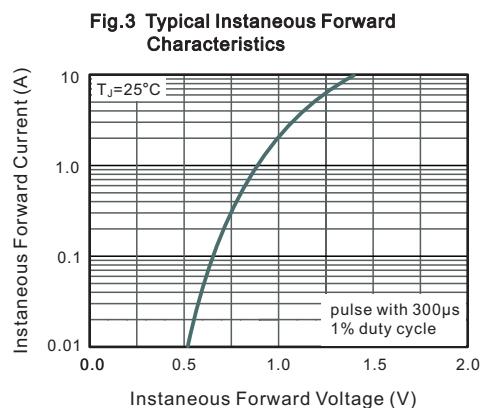
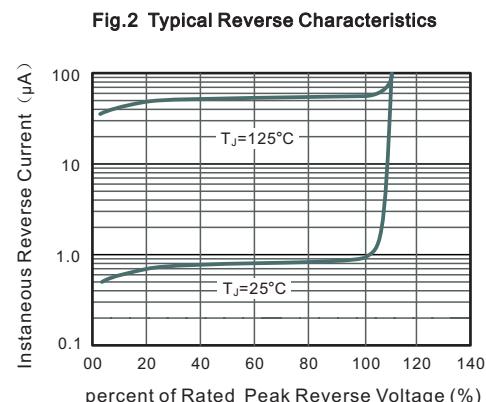
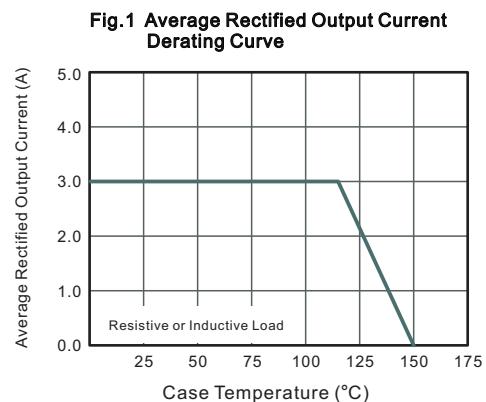
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MSB30B	MSB30D	MSB30G	MSB30J	MSB30K	MSB30M	Units
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	100	200	400	600	800	1000	V
Average Rectified Output Current	I <sub>o</sub>	3.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I <sub>FSM</sub>	80						A
Maximum Forward Voltage at 3.0 A	V <sub>F</sub>	1.1						V
Maximum DC Reverse Current @T <sub>A</sub> =25 °C at Rated DC Blocking Voltage @T <sub>A</sub> =125 °C	I <sub>R</sub>	5 100						µA
Typical Junction Capacitance ( Note1 )	C <sub>J</sub>	40						pF
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

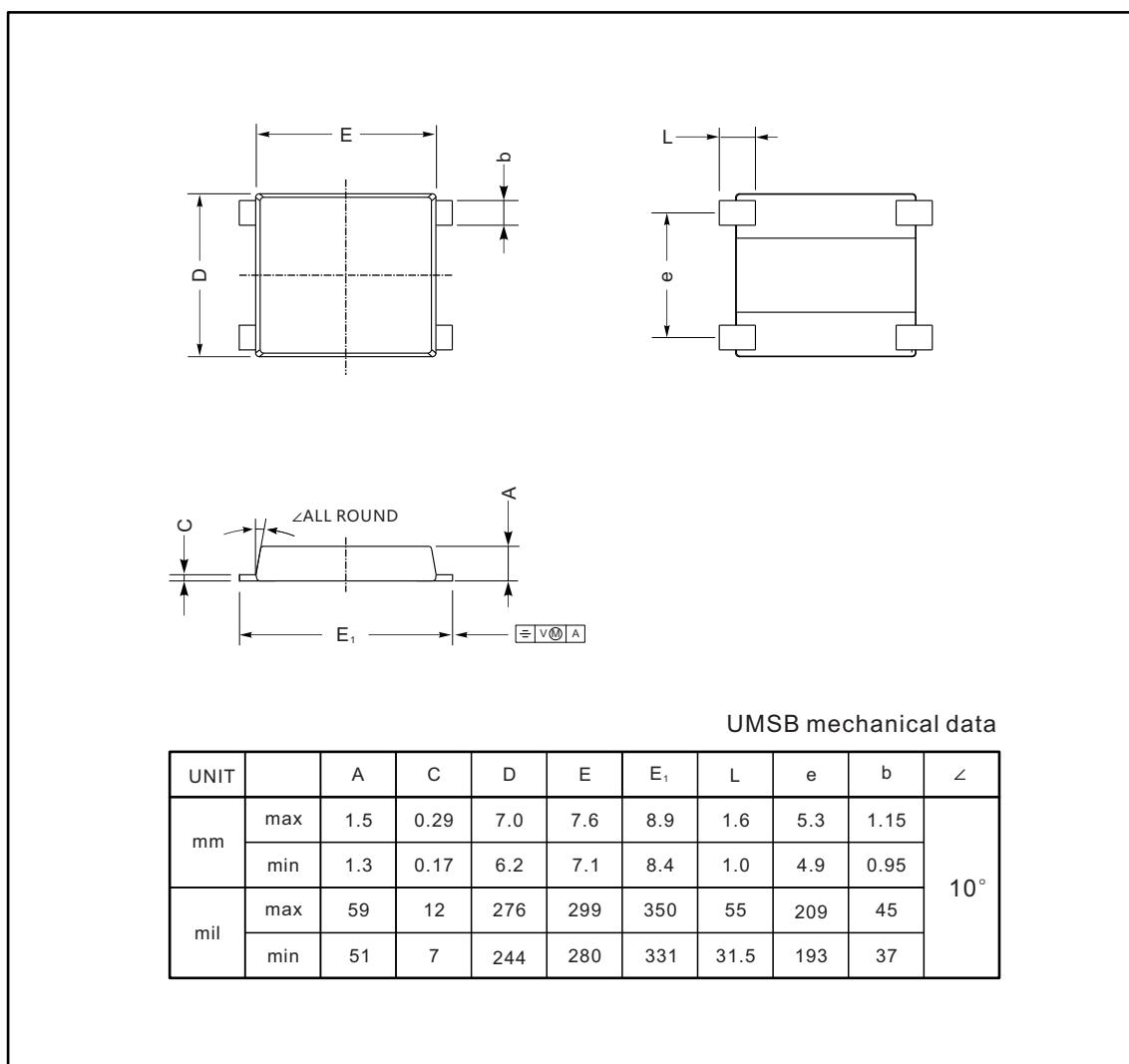




## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

UMSB



## Marking

Type number	Marking code
MSB30B	MB30B
MSB30D	MB30D
MSB30G	MB30G
MSB30J	MB30J
MSB30K	MB30K
MSB30M	MB30M

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导微\)](#)